

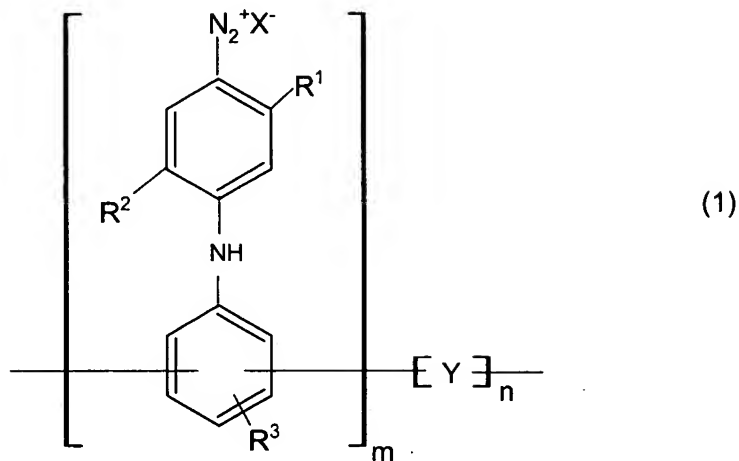
Amendments to the Claims

1 – 17. Cancelled.

18 (New). A process for the production of a negative working radiation-sensitive element comprising:

- (1) providing an optionally pretreated substrate,
- (2) applying a radiation-sensitive composition onto the substrate by means of a slot coater, wherein the radiation-sensitive composition comprises:
 - (a) at least one negative working diazo resin,
 - (b) at least one polymer with carboxyl groups soluble or swellable in an alkaline solution,
 - (c) a solvent mixture comprising:
 - (i) 2 to 9.9 wt.-% 1-methoxy-2-propanol,
 - (ii) 20 to 50 wt.-% of at least one ketone with a boiling point below 130°C,
 - (iii) 20 to 60 wt.-% of at least one alkanol with a boiling point below 120°C,
 - (iv) 10 to 30 wt.-% ethyl lactate; and
 - (d) optionally one or more additives comprising stabilizing acids, colorants, plasticizers, surfactants, thickeners or exposure indicators; and
- (3) drying.

19 (New). The process according to claim 18, wherein the negative working diazo resin is a diazo resin of formula (1):



wherein R^1 and R^2 are each independently a hydrogen atom, alkyl or alkoxy,

R^3 is a hydrogen atom, alkyl, alkoxy or $-COOR$,

R is alkyl,

X^- is an inorganic or organic anion,

Y is a spacer group which is introduced into the diazo resin by co-condensation of a monomeric diazo compound with a compound comprising aliphatic aldehydes, aromatic aldehydes, phenol ethers, aromatic thioethers, aromatic hydrocarbons, aromatic heterocycles or organic acid amides, and

m/n is 0.5 to 2.

20 (New). The process according to claim 18, wherein the polymer with carboxyl groups soluble or swellable in an alkaline solution is a polyvinyl acetal copolymer with carboxyl groups.

21 (New). The process according to claim 18, wherein the ketone of 2(c)(ii) is methyl ethyl ketone.

22 (New). The process according to claim 18, wherein the alkanol of 2(c)(iii) is methanol.

23 (New). The process according to claim 18, wherein the substrate is an aluminum plate or foil, which prior to coating is subjected to at least one treatment comprising graining, anodizing or hydrophilizing.

24 (New). The process according to claim 18, wherein the solids content of the radiation-sensitive composition is 1 to 10 wt.-%.

25 (New). The process according to claim 18, wherein the substrate is web coated at a rate of 10 to 120 m/min.

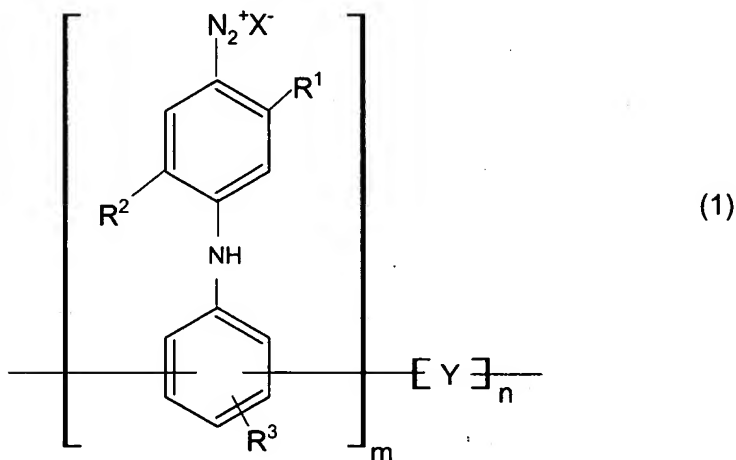
26 (New). A radiation-sensitive composition comprising:

- (a) at least one negative working diazo resin,
- (b) at least one polymer with carboxyl groups soluble or swellable in an alkaline solution,
- (c) a solvent mixture comprising:
 - (i) 2 to 9.9 wt.-% 1-methoxy-2-propanol,
 - (ii) 20 to 50 wt.-% of at least one ketone with a boiling point below 130°C,
 - (iii) 20 to 60 wt.-% of at least one alkanol with a boiling point below 120°C,
 - (iv) 10 to 30 wt.-% ethyl lactate; and
- (d) optionally one or more additives comprising stabilizing acids, colorants, plasticizers, surfactants, thickeners or exposure indicators.

27 (New). The radiation-sensitive composition according to claim 26, wherein the ketone of (c)(ii) is methyl ethyl ketone.

28 (New). The radiation-sensitive composition according to claim 26, wherein the alkanol of (c)(iii) is methanol.

- 29 (New). The radiation-sensitive composition according to claim 26, wherein the negative working diazo resin is a diazo resin of formula (1)



wherein R^1 and R^2 are each independently a hydrogen atom, alkyl or alkoxy,
 R^3 is a hydrogen atom, alkyl, alkoxy or $-COOR$,
 R is alkyl,
 X^- is an inorganic or organic anion,
 Y is a spacer group which is introduced into the diazo resin by co-condensation of a monomeric diazo compound with a compound comprising aliphatic aldehydes, aromatic aldehydes, phenol ethers, aromatic thioethers, aromatic hydrocarbons, aromatic heterocycles or organic acid amides, and
 m/n is 0.5 to 2.

- 30 (New). The radiation-sensitive composition according to claim 26, wherein the polymer with carboxyl groups soluble or swellable in an alkaline solution is a polyvinyl acetal copolymer.
- 31 (New). The radiation-sensitive composition according to claim 26, having a solid content of 1 to 10 wt.-%.

32 (New). A radiation-sensitive element produced by a process according to claim 18.

33 (New). A solvent mixture for producing a radiation-sensitive element comprising:

- (i) 2 to 9.9 wt.-% 1-methoxy-2-propanol,
- (ii) 20 to 50 wt.-% of at least one ketone with a boiling point below 130°C,
- (iii) 20 to 60 wt.-% of at least one alkanol with a boiling point below 120°C, and
- (iv) 10 to 30 wt.-% ethyl lactate.